www.vishay.com

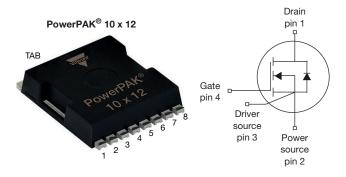
Vishay Siliconix

COMPLIANT

HALOGEN

FREE

SF Series Power MOSFET With Fast Body Diode



PRODUCT SUMMARY					
V _{DS} (V) at T _J max.	700				
R _{DS(on)} typ. (Ω) at 25 °C	$V_{GS} = 10 \text{ V}$	0.090			
Q _g max. (nC)	128				
Q _{gs} (nC)	21				
Q _{gd} (nC)	47				
Configuration	Single				

FEATURES

- · Latest generation SF series technology
- Low figure of merit (FOM) Ron x Qg
- Low effective capacitance (Co(er))
- · Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- · Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Solar (PV inverters)

ORDERING INFORMATION	
Package	PowerPAK® 10 x 12
Lead (Pb)-free and halogen-free	SiHK110N65SF-T1GE3

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)							
PARAMETER			SYMBOL	LIMIT	UNIT		
Drain-source voltage			V_{DS}	650	N/		
Gate-source voltage			V_{GS}	± 20	V		
Continuous drain current (T _J = 150 °C) ^e	V _{GS} at 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$	- I _D	34	A		
	VGS at 10 V	T _C = 100 °C		21			
Pulsed drain current ^a			I _{DM}	79	1		
Linear derating factor				2.6	W/°C		
Single pulse avalanche energy b			E _{AS}	226	mJ		
Maximum power dissipation			P_{D}	329	W		
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	°C		
Drain-source voltage slope $T_J = 125 ^{\circ}\text{C}$		dv/dt	100	V/ns			
Reverse diode dv/dt ^d			100	V/115			

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. V_{DD} = 120 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 4.0 A
- c. 1.6 mm from case
- d. $I_{SD} \le I_D$, di/dt = 850 A/ μ s, starting T_J = 25 °C
- e. Limited by maximum junction temperature



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THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient ^c	R _{thJA}	=	50	°C/W	
Maximum junction-to-case (drain)	R _{thJC}	-	0.38	G/ VV	

PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-source breakdown voltage	V _{DS}	V _{GS} =	650	-	-	V	
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	Reference to 25 °C, I _D = 1 mA		0.62	-	V/°C
Gate-source threshold voltage (N)	V _{GS(th)}	V _{DS} =	V _{DS} = V _{GS} , I _D = 250 μA		-	5.0	٧
Gate-source leakage	I _{GSS}	,	$V_{GS} = \pm 20 \text{ V}$		-	± 100	nA
		V _{DS} =	$V_{DS} = 650 \text{ V}, V_{GS} = 0 \text{ V}$		-	1	μΑ
Zero gate voltage drain current	I _{DSS}	V _{DS} = 520 V	V _{DS} = 520 V, V _{GS} = 0 V, T _J = 125 °C		-	2	mA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 17.5 A	-	0.090	0.110	Ω
Forward transconductance ^a	9 _{fs}	V _{DS} =	= 20 V, I _D = 17.5 A	-	16	-	S
Dynamic		•					
Input capacitance	C _{iss}		-	2795	-	pF	
Output capacitance	C _{oss}	$V_{GS} = 0 \text{ V},$ $V_{DS} = 100 \text{ V},$ f = 100 KHz		-	91		-
Reverse transfer capacitance	C _{rss}			-	2		-
Effective output capacitance, energy related ^a	C _{o(er)}	V _{DS} = 0 V to 400 V, V _{GS} = 0 V		-	96		-
Effective output capacitance, time related ^b	$C_{o(tr)}$			-	461		-
Total gate charge	Qq			-	85	128	
Gate-source charge	Q _{gs}	V _{GS} = 10 V	$V_{GS} = 10 \text{ V}$ $I_{D} = 17.5 \text{ A}, V_{DS} = 520 \text{ V}$		21	-	nC
Gate-drain charge	Q _{gd}	7		-	47	-	1
Turn-on delay time	t _{d(on)}		•	-	32	64	
Rise time	t _r	V _{DD} =	V _{DD} = 520 V, I _D = 17.5 A,		44	88	- ns
Turn-off delay time	t _{d(off)}	$V_{GS} = 10 \text{ V}, R_g = 10.1 \Omega$		-	90	135	
Fall time	t _f			-	17	34	
Gate input resistance	R _g	f = 1 MHz, open drain		0.6	1.2	2.4	Ω
Drain-Source Body Diode Characteristic							
Continuous source-drain diode current	I _S	showing the	MOSFET symbol showing the		-	34	
Pulsed diode forward current	I _{SM}	integral reverse p - n junction diode		-	-	79	A
Diode forward voltage	V _{SD}	T _J = 25 °C, I _S = 17.5 A, V _{GS} = 0 V		-	-	1.4	V
Reverse recovery time	t _{rr}	T _J = 25 °C, I _F = I _S = 17.5 A, di/dt = 100 A/µs, V _R = 400 V		-	155	310	ns
Reverse recovery charge	Q _{rr}			-	0.9	1.8	μC
Reverse recovery current	I _{RRM}			_	9.7	_	Α

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 V to 400 V
- b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 V to 400 V
- c. When mounted on 1" x 1" FR4 board



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

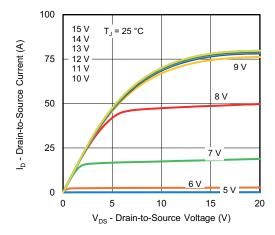


Fig. 1 - Typical Output Characteristics

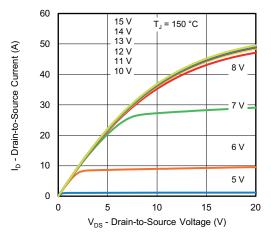


Fig. 2 - Typical Output Characteristics

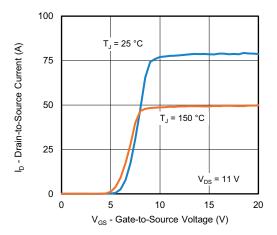


Fig. 3 - Typical Transfer Characteristics

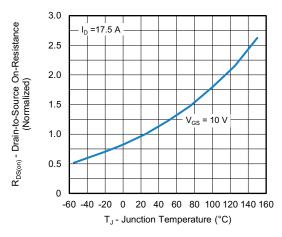


Fig. 4 - Normalized On-Resistance vs. Temperature

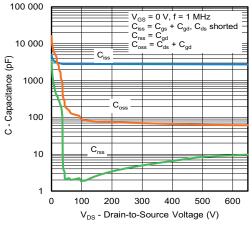


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

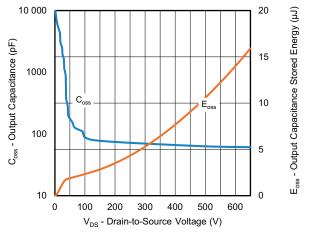


Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}



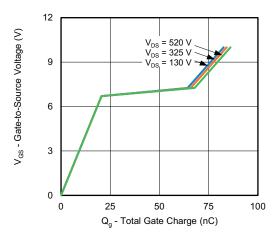


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

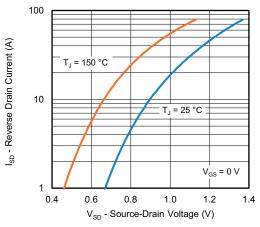


Fig. 8 - Typical Source-Drain Diode Forward Voltage

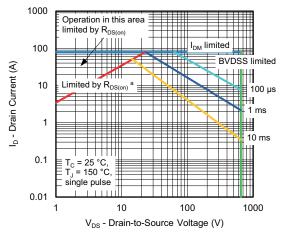


Fig. 9 - Maximum Safe Operating Area

Note

a. $V_{GS} > minimum \ V_{GS}$ at which $R_{DS(on)}$ is specified

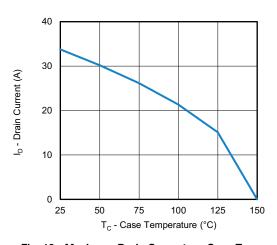


Fig. 10 - Maximum Drain Current vs. Case Temperature

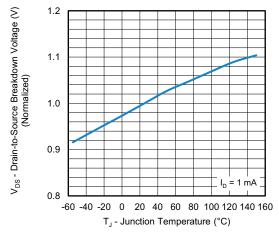


Fig. 11 - Temperature vs. Drain-to-Source Voltage



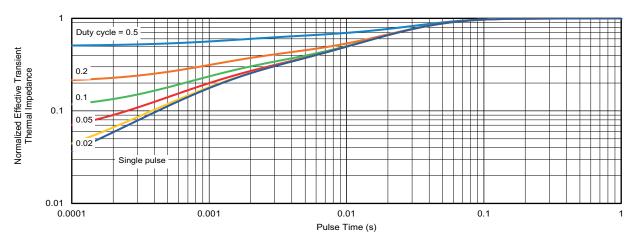


Fig. 12 - Normalized Transient Thermal Impedance, Junction-to-Case

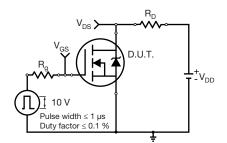


Fig. 13 - Switching Time Test Circuit

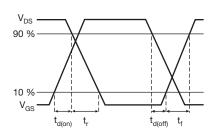


Fig. 14 - Switching Time Waveforms

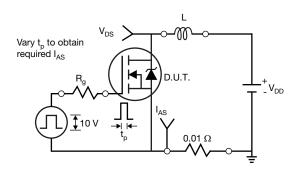


Fig. 15 - Unclamped Inductive Test Circuit

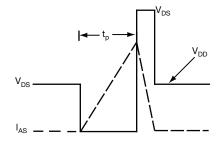


Fig. 16 - Unclamped Inductive Waveforms

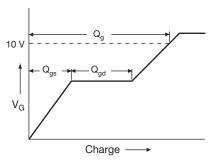


Fig. 17 - Basic Gate Charge Waveform

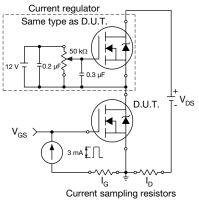
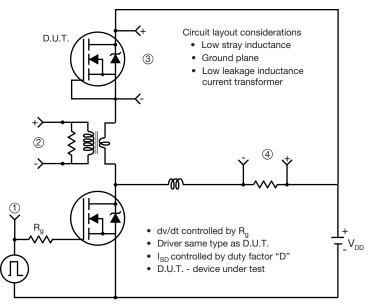


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dv/dt Test Circuit



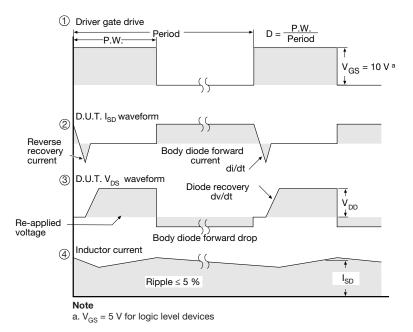


Fig. 19 - For N-Channel

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